

Notice of References Cited

Application/Control No.

09/510,828

Applicant(s)/Patiént Under

Reexamination

HEMBREE ET AL.9

Examiner

James Mitchell

Art Unit

2827

Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,229,320	05-2001	Haseyama et al.	324/754
	B	US-6,229,320	05-2001	Haseyama et al.	324/754
	C	US-4,340,860	07-1982	Teeple, Jr., Lawrence R.	200/245
	D	US-6,333,638	12-2001	Fukasawa et al.	324/754
	E	US-5,497,103	03-1996	Ebert et al.	324/754
	F	US-5,175,613	12-1992	Barker et al.	174/35GC
	G	US-5,500,556	03-1996	Kosugi, Yuhei	257/718
	H	US-4,916,523	04-1990	Sokolovsky et al.	174/52.1
	I	US-6,411,116	06-2002	DeHaven et al.	324/754
	J	US-4,998,885	03-1991	Beaman, Brian S.	439/541
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	IBM Technical Disclosure, "Cooling and Minimizing Temperature Gradient in Stacked Modules", Vol 19, Issue 2, Page 414, July 1, 1976
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.